BTH151S-650R

### **GENERAL DESCRIPTION**

Passivated thyristor in a plastic envelope, suitable for surface mounting, intended for use in applications requiring high bidirectional blocking voltage capability and high thermal cycling performance. This thyristor has a high repetitive surge specification which makes it suitable for applications where high inrush currents or stall currents are likely to occur on a repetitive basis.

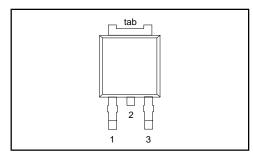
### **QUICK REFERENCE DATA**

SYMBOL	PARAMETER	MAX.	UNIT
V <sub>DRM</sub> , V <sub>RRM</sub> I <sub>T(AV)</sub> I <sub>T(RMS)</sub> I <sub>TSM</sub> I <sub>TRM</sub>	Repetitive peak off-state voltages Average on-state current RMS on-state current Non-repetitive peak on-state current Repetitive peak on-state current	650 7.5 12 110 60	V A A A

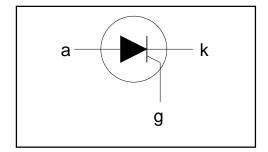
### **PINNING - SOT428**

PIN DESCRIPTION	
1	cathode
2	anode
3	gate
tab	anode
	I .

### **PIN CONFIGURATION**



### **SYMBOL**



### LIMITING VALUES

Limiting values in accordance with the Absolute Maximum System (IEC 134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
$V_{DRM}$ , $V_{RRM}$	Repetitive peak off-state voltages	half sine wave;	-	<sup>1</sup> 650	V
I <sub>T(AV)</sub>	Average on-state current	T <sub>mb</sub> ≤ 103 °C	-	7.5	A
I <sub>T(RMS)</sub> I <sub>TSM</sub>	RMS on-state current Non-repetitive peak on-state current	all conduction angles half sine wave; $T_j = 25$ °C prior to surge	-	12	A
	on state current	t = 10 ms	-	110	A
		t = 8.3  ms	-	121	A
I <sub>TRM</sub>	Repetitive peak on-state current	$t = 10$ ms, $\tau = 3$ s, $T_{mb} \le 45$ °C, no. of surges = 100k	-	60	A
l <sup>2</sup> t	I <sup>2</sup> t for fusing	t = 10 ms	-	61	A <sup>2</sup> s
dl <sub>⊤</sub> /dt	Repetitive rate of rise of on-state current after	$I_{TM}$ = 20 A; $I_G$ = 50 mA; $dI_G/dt$ = 50 mA/ $\mu$ s	-	50	A/μs
I <sub>GM</sub>	triggering Peak gate current		_	2	A
V <sub>GM</sub>	Peak gate voltage		-	5	l v l
V <sub>RGM</sub>	Peak reverse gate voltage		-	5	l v l
$IP_{GM}$	Peak gate power		-	5	W
P <sub>G(AV)</sub>	Average gate power	over any 20 ms period	-	0.5	W
T <sub>sta</sub>	Storage temperature	'	-40	150	l °C ∣
$T_{j}^{\text{stg}}$	Operating junction		-	125	°C
'	temperature				

March 2001 1 Rev 1.001

<sup>1</sup> Although not recommended, off-state voltages up to 800V may be applied without damage, but the thyristor may switch to the on-state. The rate of rise of current should not exceed 15  $A/\mu s$ .

BTH151S-650R

### THERMAL RESISTANCES

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
R <sub>th j-mb</sub>	Thermal resistance			-	1.8	K/W
R <sub>th j-a</sub>	junction to mounting base Thermal resistance junction to ambient	pcb (FR4) mounted; footprint as in Fig.14	-	75	-	K/W

## STATIC CHARACTERISTICS

 $T_i = 25$  °C unless otherwise stated

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
I <sub>GT</sub>	Gate trigger current	$V_D = 12 \text{ V}; I_T = 0.1 \text{ A}$	-	2	15	mΑ
l IĽ	Latching current	$V_D = 12 \text{ V}; I_{GT} = 0.1 \text{ A}$	-	10	40	mΑ
I <sub>H</sub>	Holding current	$V_D = 12 \text{ V}; I_{GT} = 0.1 \text{ A}$	-	7	20	mΑ
Ϊ́Τ	On-state voltage	$I_{T} = 23 \text{ A}$	-	1.4	1.75	V
V <sub>GT</sub>	Gate trigger voltage	$\dot{V}_{D} = 12 \text{ V}; I_{T} = 0.1 \text{ A}$	-	0.6	1.5	V
		$V_D = V_{DRM(max)}$ ; $I_T = 0.1 \text{ A}$ ; $T_j = 125 ^{\circ}\text{C}$	0.25	0.4	-	V
$I_D, I_R$	Off-state leakage current	$V_D = V_{DRM(max)}$ ; $V_R = V_{RRM(max)}$ ; $T_j = 125$ °C	-	0.1	0.5	mA

### **DYNAMIC CHARACTERISTICS**

T<sub>i</sub> = 25 °C unless otherwise stated

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
dV <sub>D</sub> /dt	Critical rate of rise of off-state voltage	V <sub>DM</sub> = 67% V <sub>DRM(max)</sub> ; T <sub>j</sub> = 125 °C; exponential waveform;				
		Gate open circuit	50	130	-	V/μs
		$R_{GK} = 100 \Omega$	200	1000	-	V/μs
$\mathbf{t}_{\mathrm{gt}}$	Gate controlled turn-on time	$I_{TM} = 40 \text{ A}; V_D = V_{DRM(max)}; I_G = 0.1 \text{ A};$ $dI_G/dt = 5 \text{ A}/\mu \text{s}$	-	2	-	μs
t <sub>q</sub>	Circuit commutated turn-off time	$V_D = 67\% \ V_{DRM(max)}; T_j = 125 \ ^{\circ}C;$ $I_{TM} = 20 \ A; V_R = 25 \ V; dI_{TM}/dt = 30 \ A/\mu s;$ $dV_D/dt = 50 \ V/\mu s; R_{GK} = 100 \ \Omega$	-	70	-	μs

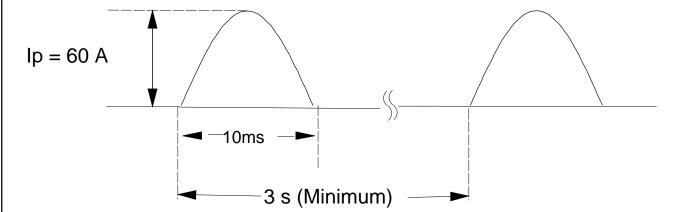


Fig.1. Repetitive surge conditions.  $I_P$ =60A (f=50Hz) at Tc=45°C. Maximum number of cycles n=100k. Repetitive cycle T=3 seconds minimum.

BTH151S-650R

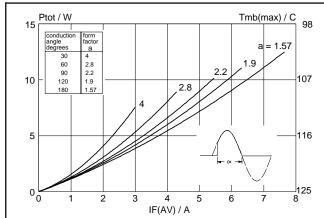


Fig.2. Maximum on-state dissipation,  $P_{tot}$ , versus average on-state current,  $I_{T(AV)}$ , where  $a = form\ factor = I_{T(RMS)}/I_{T(AV)}$ .

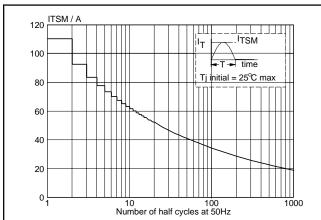


Fig.5. Maximum permissible non-repetitive peak on-state current  $I_{TSM}$ , versus number of cycles, for sinusoidal currents, f = 50 Hz.

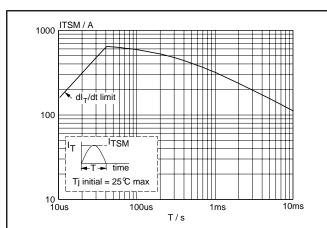


Fig.3. Maximum permissible rms current  $I_{T(RMS)}$ , versus mounting base temperature  $T_{mb}$ .

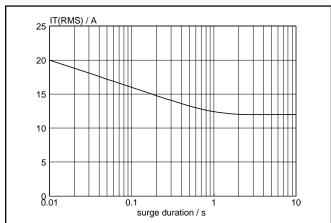


Fig.6. Maximum permissible repetitive rms on-state current  $I_{T(RMS)}$ , versus surge duration, for sinusoidal currents, f = 50 Hz;  $T_{mb} \le 103$  °C.

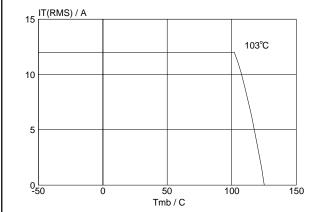
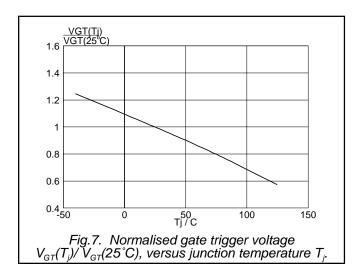
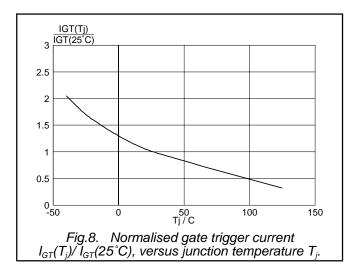
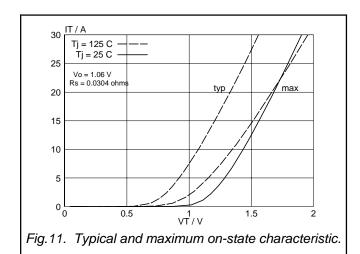


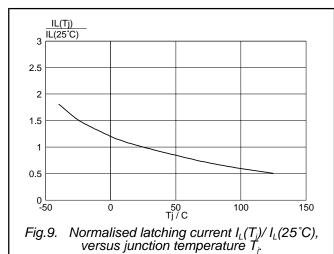
Fig.4. Maximum permissible rms current  $I_{T(RMS)}$ , versus mounting base temperature  $T_{mb}$ .

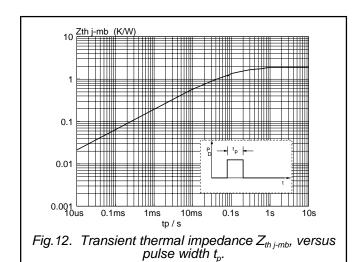


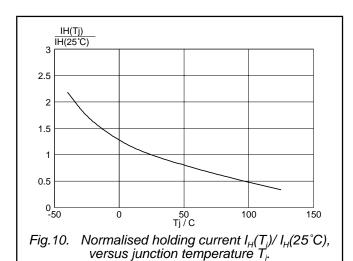
BTH151S-650R











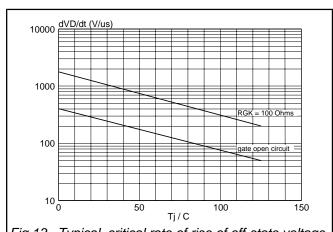
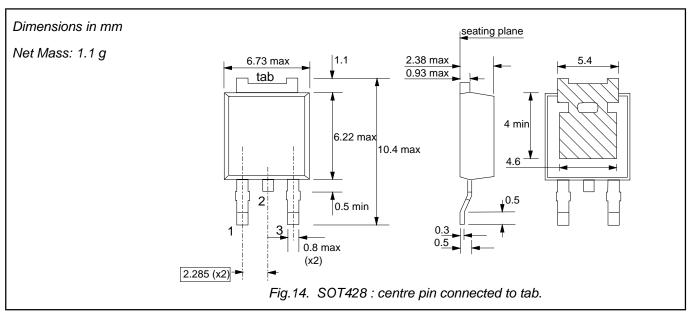


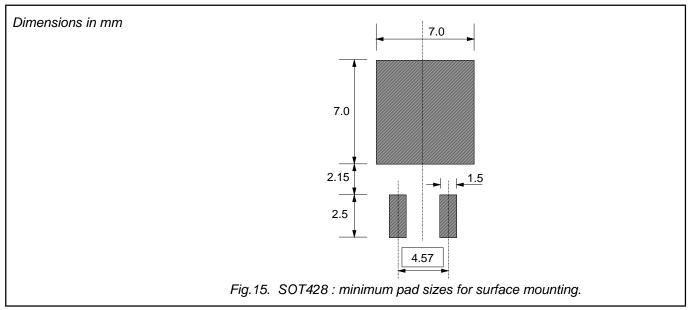
Fig.13. Typical, critical rate of rise of off-state voltage, dV<sub>D</sub>/dt versus junction temperature T<sub>j</sub>.

BTH151S-650R

### **MECHANICAL DATA**



## **MOUNTING INSTRUCTIONS**



### **Notes**

1. Plastic meets UL94 V0 at 1/8".

BTH151S-650R

### **DEFINITIONS**

Data sheet status				
Objective specification	This data sheet contains target or goal specifications for product development.			
Preliminary specification	This data sheet contains preliminary data; supplementary data may be published later.			
Product specification This data sheet contains final product specifications.				

#### Limiting values

Limiting values are given in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of this specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

#### **Application information**

Where application information is given, it is advisory and does not form part of the specification.

### © Philips Electronics N.V. 2001

All rights are reserved. Reproduction in whole or in part is prohibited without the prior written consent of the copyright owner.

The information presented in this document does not form part of any quotation or contract, it is believed to be accurate and reliable and may be changed without notice. No liability will be accepted by the publisher for any consequence of its use. Publication thereof does not convey nor imply any license under patent or other industrial or intellectual property rights.

#### LIFE SUPPORT APPLICATIONS

These products are not designed for use in life support appliances, devices or systems where malfunction of these products can be reasonably expected to result in personal injury. Philips customers using or selling these products for use in such applications do so at their own risk and agree to fully indemnify Philips for any damages resulting from such improper use or sale.